PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takaya YAMAMOTO	12/27/2007
Tatsuji MATSUURA	12/27/2007
Masumi KASAHARA	12/27/2007
Hideo NAKANE	12/27/2007
Junya KUDO	12/27/2007
Yoshitaka JINGU	12/27/2007

RECEIVING PARTY DATA

Name:	RENESAS TECHNOLOGY CORP.
Street Address:	6-2, Otemachi 2-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12013855

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CORRESPONDENCE DATA

Fax Number:	(703)684-1157

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone:	7036841120
Email:	sbarber@msmbpatentlaw.com
Correspondent Name:	Daniel J. Stanger
Address Line 1:	1800 Diagonal Road, Suite 370
Address Line 4:	Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	TAM-6172
NAME OF SUBMITTER:	Daniel J. Stanger

Total Attachments: 1
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ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by RENESAS TECHNOLOGY CORP., a corporation organized under the laws of Japan, located at 6-2 , Otemachi 2-chome , Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said RENESAS TECHNOLOGY CORP., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said RENESAS TECHNOLOGY CORP., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said RENESAS TECHNOLOGY CORP.,

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)
1)	Takaya Yamamoto	(Takaya YAMAMOTO)	27 / December / 2007
2)	Tatsuji Matsuura	(Tatsuji MATSUURA)	27 / December / 2007
3)	Masumi Kasahara	(Masumi KASAHARA)	27/December/2007
4)	Hideo Nakane	(Hideo NAKANE)	27 / December / 2007
5)	Junya Kudo	(Junya KUDO)	27 / December / 2007
6)	Yoshitaka Jingu	(Yoshitaka JINGU)	27 / December / 2007
7)			
8)			